

MINIDIP



PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.4 mm	3.9 W/cm°C
die attach	soft solder (tin / lead)	15-50 µm	0.2 W/cm°C
molding compound	epoxy resin	3 mm	0.0063W/cm°C

Charts enclosed :

- 1) $R_{th(j-a)}$ vs power dissipation
- 2) $Z_{th(j-a)}$ vs time width and die size

